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(54) METHOD AND APPARATUS FOR PICKING UP WORKPIECE AND MOUNTING MACHINE

(57)Abstract:

PROBLEM TO BE SOLVED: To provide a method and an apparatus for picking up a workpiece such as a chip which can avoid the possibility of damage of the workpiece, and a mounting machine therefor.

SOLUTION: The workpiece pickup method comprises steps of sucking and holding a workpiece bonded to an adhesive sheet, peeling the workpiece off from the sheet and transporting the workpiece, with use of a sucking collet disposed to be moved up and down above the workpiece bonded to the adhesive sheet for sucking and holding the workpiece and a sucking member disposed to be moved up and down under the adhesive sheet for sucking and holding the adhesive sheet. In the method, the lower surface of the adhesive sheet corresponding to the workpiece is sucked and held by the sucking member (sheet sucking step), the workpiece is sucked, held and peeled off by the sucking collet in a positional relationship between the sucking collet and the workpiece (workpiece sucking step).

